INTEGRATED CIRCUITS



Product data sheet Replaces data sheet 74F543/74F544 of 1994 Dec 05 2004 Jul 22



74F543

FEATURES

- Combines74F245 and 74F373 type functions in one chip
- 8-bit octal transceiver with D-type latch
- Back-to-back registers for storage
- Separate controls for data flow in each direction
- A outputs sink 20 mA and source 3 mA
- B outputs sink 64 mA and source 15 mA
- 3-State outputs for bus-oriented applications
- Available in SSOP Type II package

DESCRIPTION

The 74F543 Octal Registered Transceiver contains two sets of D-type latches for temporary storage of data flowing in either direction. Separate Latch Enable (LEAB, LEBA) and Output Enable (OEAB, OEBA) inputs are provided for each register to permit independent control of inputting and outputting in either direction of data flow. The A outputs are guaranteed to sink 24 mA, while the B outputs are rated for 64 mA.

ORDERING INFORMATION

Commerical range: V_{CC} = 5 V ± 10 %; T_{amb} = 0 °C to +70 °C

FUNCTIONAL DESCRIPTION

The 74F543 contains two sets of eight D-type latches, with separate input and controls for each set. For data flow from A to B, for example, the A-to-B Enable (EAB) input must be LOW in order to enter data from A0 - A7 or take data from B0 - B7, as indicated in the Function Table. With EAB LOW, a LOW signal on the A-to-B Latch Enable (LEAB) input makes the A-to-B latches transparent; a subsequent LOW-to-HIGH transition for the LEAB signal puts the A latches in the storage mode and their outputs no longer change with the A inputs. With EAB and OEAB both LOW, the 3-State B output buffers are active and display the data present at the outputs of the A latches. Control of data flow from B to A is similar, but using the EBA, LEBA, and OEBA inputs.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F543	6.0 ns	80 mA

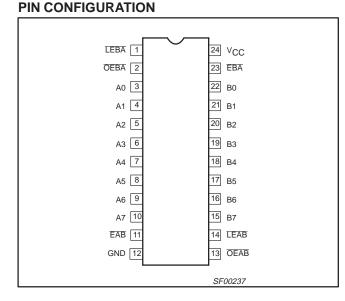
Type number	Package	Package								
	Name	Description	Version							
N74F543D	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1							
N74F543DB	SSOP24	plastic shrink small outline pacakge; 24 leads; body width 5.3 mm	SOT340-1							
N74F543N	DIP24	plastic dual in-line package; 24 leads (300 mil)	SOT222-1							

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

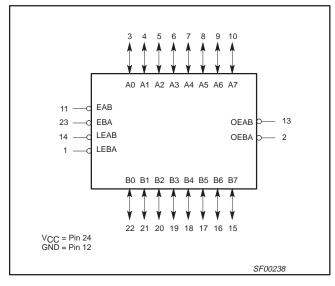
PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW	
A0 - A7	Port A, 3-State inputs	3.5/1.0	70 μA/0.6 mA	
B0 - B7	Port B, 3-State inputs	3.5/1.0	70 μA/0.6 mA	
OEAB	A-to-B Output Enable input (Active LOW)	1.0/1.0	20 μA/0.6 mA	
OEBA	B-to-A Output Enable input (Active LOW)	1.0/1.0	20 μA/0.6 mA	
EAB	A-to-B Enable input (Active LOW)	1.0/2.0	20 μA/1.2 mA	
EBA	B-to-A Enable input (Active LOW)	1.0/2.0	20 μA/1.2 mA	
LEAB	A-to-B Latch Enable input (Active LOW)	1.0/1.0	20 μA/0.6 mA	
LEBA	B-to-A Latch Enable input (Active LOW)	1.0/1.0	20 μA/0.6 mA	
A0 - A7	Port A, 3-State outputs	150/40	3.0 mA/24 mA	
B0 - B7	Port B, 3-State outputs	750/106.7	15 mA/64 mA	

NOTE: One (1.0) FAST Unit Load is defined as: 20 µA in the HIGH State and 0.6mA in the LOW state.

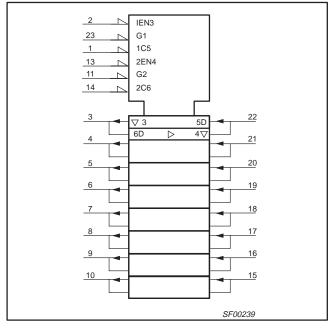
74F543



LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE for 74F543

	INP	UTS			STATUS
OEXX	EXX	LEXX	DATA	OUTPUTS	
Н	Х	Х	Х	Z	Disabled
Х	Н	Х	Х	Z	Disabled
L	\uparrow	L	h	Z	Disable +
L	\uparrow	L	I	Z	Latch
L	L	\uparrow	h	Н	Latch +
L	L	\uparrow	I	L	Display
L	L	L	Н	Н	Transparent
L	L	L	L	L	Hansparent
L	L	Н	Х	NC	Hold

= HIGH voltage level Н

LOW voltage level L =

HIGH state must be present one setup time before the h = LOW-to-HIGH transition of LEXX or EXX (XX=AB or BA)

LOW state must be present one setup time before the LOW-to-HIGH transition of LEXX or EXX (XX=AB or BA) =

↑ = LOW-to-HIGH transition of $\overline{\text{LEXX}}$ or $\overline{\text{EXX}}$ XX = AB or BA

= Don't care Х

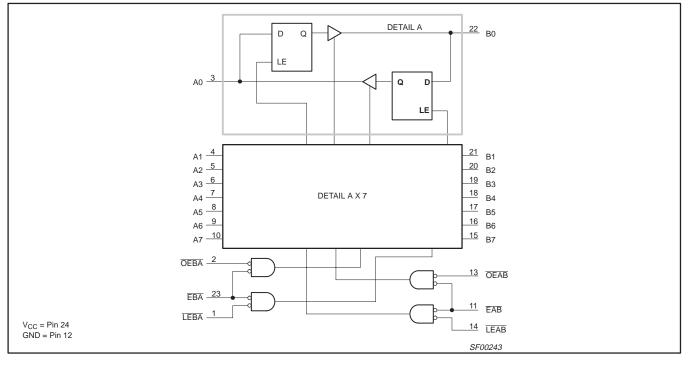
NC = No change

Т

Ζ = High-impedance "off" state

74F543

LOGIC DIAGRAM



74F543

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V _{CC}	Supply voltage		-0.5 to +7.0	V
V _{IN}	Input voltage	-0.5 to +7.0	V	
I _{IN}	Input current	-30 to +5	mA	
V _{OUT}	Voltage applied to output in HIGH output state	-0.5 to +5.5	V	
		A0 - A7	48	mA
IOUT	Current applied to output in LOW output state	B0 - B7	128	mA
T _{amb}	Operating free-air temperature range	÷	0 to +70	°C
T _{stg}	Storage temperature		-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER			UNIT		
STWIDOL	FARAMETER		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		4.5	5.0	5.5	V
V _{IH}	HIGH-level input voltage		2.0	-	-	V
V _{IL}	LOW-level input voltage		-	-	0.8	V
I _{IK}	Input clamp current		-	-	-18	mA
		A0 - A7	-	-	-3	mA
юн	HIGH-level output current	B0 - B7	-	-	-15	mA
		A0 - A7	-	-	24	mA
I _{OL}	LOW-level output current	B0 - B7	-	_	64	mA
T _{amb}	Operating free-air temperature range		-0	_	+70	°C

74F543

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

	DADAMET					LIMITS			UNIT
SYMBOL	PARAMETI	=K		EST CONDITION	12,	MIN	TYP ²	MAX	
		40.47		1 0 m A	±10 % V_{CC}	2.4	-	-	V
N/	HIGH-level output voltage	A0 - A7	$V_{CC} = MIN$ $V_{IL} = MAX$	I _{OH} = -3 mA	± 5 % V _{CC}	2.7	3.4	-	V
V _{OH}		B0 - B7	$V_{\rm IL} = MIN$	1 – 15 mA	\pm 10 % V_{CC}	2.0	-	-	V
		BU - B7	• IH = IIII 4	I _{OH} = -15 mA	\pm 5 % V _{CC}	2.0	-	-	V
		A0 - A7		1 04 mA	\pm 10 % V_{CC}	-	0.35	0.50	V
V		A0 - A7	$V_{CC} = MIN$ $V_{II} = MAX$	I _{OL} = 24 mA	±5 % V_{CC}	-	0.35	0.50	V
V _{OL}	LOW-level output voltage	B0 - B7	$V_{\rm IL} = MIN$	1 - 64 mA	\pm 10 % V_{CC}	-	-	0.55	V
		B0 - B7		I _{OL} = 64 mA	±5 % V_{CC}	-	0.42	0.55	V
V _{IK}	Input clamp voltage		V _{CC} = MIN; I	I = I _{IK}		-	-0.73	-1.2	V
	Input current at maximum	OEAB, OEBA, EAB	$V_{CC} = MAX;$	V _I = 7.0 V	-	-	100	μΑ	
łı	input voltage	Others	V _{CC} = 5.5 V;	V _I = 5.5 V	-	-	1	mA	
I _{IH}	HIGH-level input current		$V_{CC} = MAX;$	V _I = 2.7 V	-	-	20	μΑ	
L.	LOW-level input current	Others	V _{CC} = MAX;	V 0 5 V	-	-	-0.6	mA	
ΙL		EAB, EBA	$v_{\rm CC} = war,$	v =0.5 v		-	-	-1.2	mA
I _{OZH} + I _{IH}	Off-state output current, HIGH-	level voltage applied	V _{CC} = MAX;	V _O = 2.7 V		-	-	70	μΑ
I _{OZH} + I _{IL}	Off-state output current, LOW-	evel voltage applied	V _{CC} = MAX;	V _O = 0. 5 V		-	-	-600	μΑ
1	Short airquit autaut aurrant ³	A0 - A7				-60	-	-150	mA
IOS	Short-circuit output current ³	B0 - B7	$V_{CC} = MAX$			-100	-	-225	mA
		I _{ССН}				-	70	105	mA
I _{CC}	Supply current (total)	ICCL	$V_{CC} = MAX$			-	95	135	mA
		I _{CCZ}]			-	95	135	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under the recommended operating conditions for the applicable type.

2.

All typical values are at $V_{CC} = 5 \text{ V}$, $T_{amb} = 25 \text{ °C}$. Not more than one output should be shorted at a time. For testing I_{OS} , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting 3. of a HIGH output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

74F543

AC ELECTRICAL CHARACTERISTICS

					LIM	ITS		
SYMBOL	PARAMETER	TEST CONDITIONS	۱ N	_{mb} = +25 [•] / _{CC} = 5.0 [•]) pF; R _L =	/	T _{amb} = 0 °C V _{CC} = 5.0 C _L = 50pF;	UNIT	
			MIN	ТҮР	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay A _n to B _n	Waveform 1	3.5 3.0	5.5 5.0	8.5 8.0	3.0 2.5	9.0 8.5	ns
t _{PLH} t _{PHL}	Propagation delay B_n to A_n	Waveform 1	2.5 2.5	4.0 4.5	7.0 7.5	2.5 2.5	7.5 8.0	ns
t _{PLH} t _{PHL}	Propagation delay LEBA to A _n	Waveform 1	5.0 4.0	7.0 6.0	10.0 9.0	4.5 4.0	11.0 9.5	ns
t _{PLH} t _{PHL}	Propagation delay LEAB to B _n	Waveform 1	6.0 4.5	8.5 6.5	11.5 9.5	5.5 4.0	12.5 10.0	ns
t _{PZH} t _{PZL}	$\frac{\text{Output Enable time}}{\text{OEBA} \text{ to } A_n \text{ or } \overline{\text{OEAB}} \text{ to } B_n$	Waveform 3 Waveform 4	2.0 3.5	4.0 5.0	7.5 8.5	1.5 3.0	8.0 9.0	ns
t _{PHZ} t _{PLZ}	$\frac{\text{Output Disable time}}{\text{OEBA} \text{ to } A_n \text{ or } \overline{\text{OEAB}} \text{ to } B_n$	Waveform 3 Waveform 4	1.0 1.5	3.0 4.0	6.5 7.5	1.0 1.0	7.5 8.5	ns
t _{PZH} t _{PZL}	Output Enable time EBA to A _n or EAB to B _n	Waveform 3 Waveform 4	4.5 5.0	7.0 7.0	10.5 10.5	4.0 4.5	11.5 11.0	ns
t _{PHZ} t _{PLZ}	Output Disable time EBA to A_n or EAB to B_n	Waveform 3 Waveform 4	2.5 4.5	5.0 7.0	8.5 11.0	2.0 3.0	9.5 12.0	ns

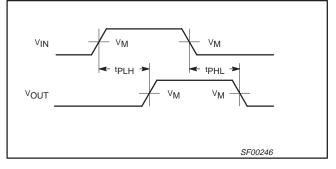
AC SETUP REQUIREMENTS

SYMBOL	PARAMETER	TEST CONDITIONS	T _{amb} = V _{CC} = C _L = 50 pF;		T _{amb} = 0 °C V _{CC} = 5.0 C _L = 50 pF;	UNIT	
			MIN	TYP	MIN	MAX	
t _s (H) t _s (L)	Setup time, HIGH or LOW A_n to LEAB or B_n to LEAB	Waveform 2	0.0 2.5		0.0 3.0		ns
t _h (H) t _h (L)	Hold time, HIGH or LOW A_n to LEAB or B_n to LEAB	Waveform 2	0.0 1.5		0.0 2.0		ns
t _s (H) t _s (L)	Setup time, HIGH or LOW A_n to EAB or B_n to EBA	Waveform 2	1.0 2.5		1.5 3.0		ns
t _h (H) t _h (L)	Hold time, HIGH or LOW A_n to EAB or B_n to EBA	Waveform 2	0.0 1.5		0.0 2.0	_	ns
t _w (L)	Latch enable pulse width, LOW	Waveform 2	4.0	_	4.5	_	ns

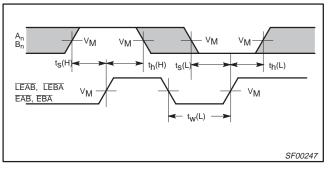
74F543

AC WAVEFORMS

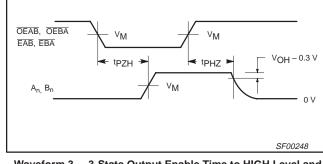
 V_{M} = 1.5 V. The shaded areas indicate when the input is permitted to change for predictable output performance.



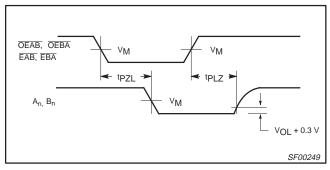




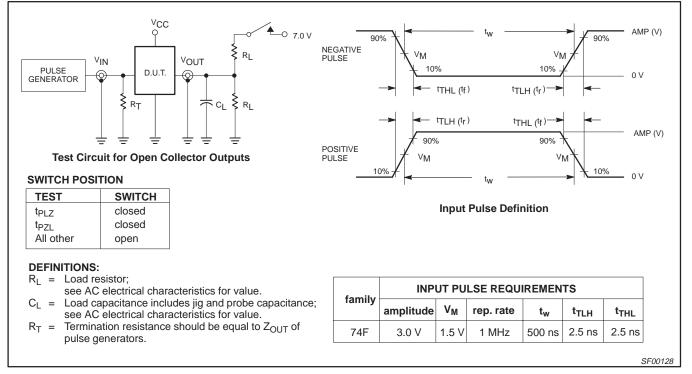
Waveform 2. Data Setup Time and Hold Times, and Latch Enable Pulse Width



Waveform 3. 3-State Output Enable Time to HIGH Level and Output Disable Time from HIGH Level

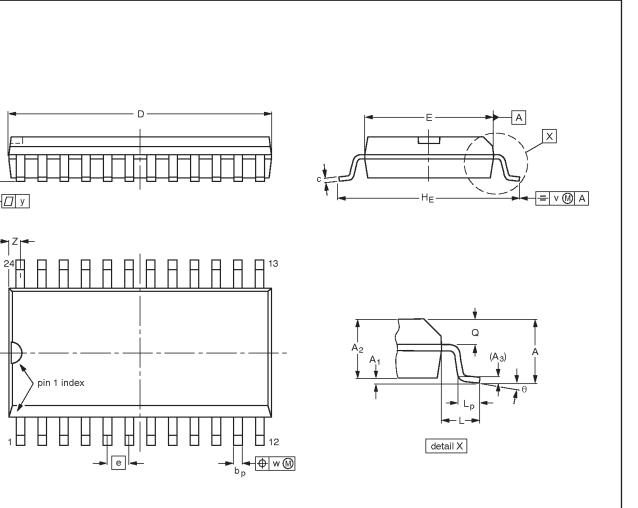


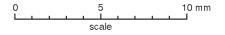
Waveform 4. 3-State Output Enable Time to LOW Level and Output Disable Time from LOW Level



TEST CIRCUIT AND WAVEFORMS

SO24: plastic small outline package; 24 leads; body width 7.5 mm





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	с	D ⁽¹⁾	E ⁽¹⁾	e	Η _E	L	Lp	Q	v	w	У	z ⁽¹⁾	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8 ⁰
inches	0.1	0.012 0.004		0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

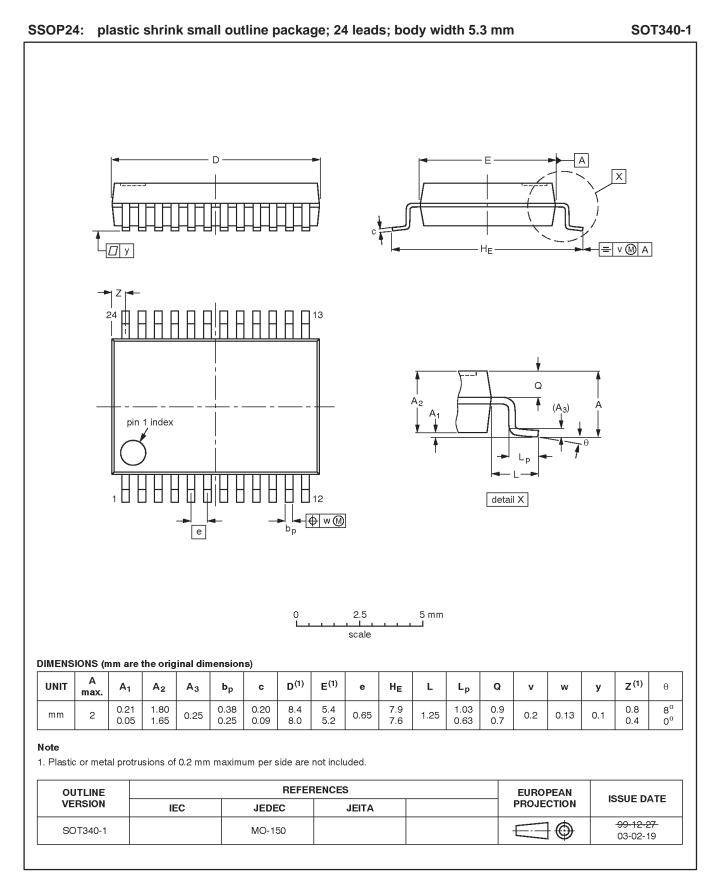
1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

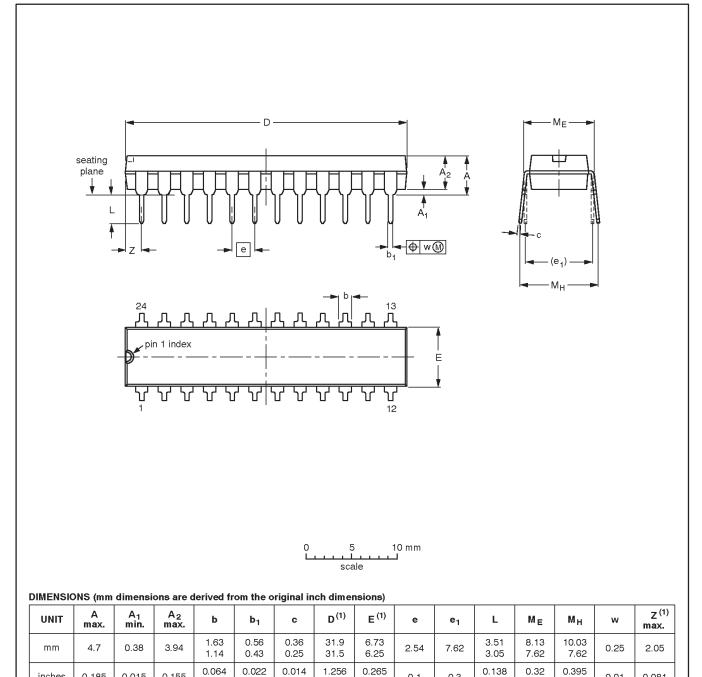
OUTLINE					EUROPEAN		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT137-1	075E05	MS-013				-99-12-27 03-02-19	

SOT137-1

74F543

Product data sheet





Note

inches

0.185

0.015

0.155

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

0.045

0.017

0.010

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT222-1		MS-001				-99-12-27- 03-03-12	

1.240

0.246

0.1

0.3

0.120

0.30

0.300

74F543

SOT222-1

0.01

0.081

74F543

REVISION HISTORY

Rev	Date	Description	
_3	20040722	Product data sheet (9397 750 13803). Replaces Product specification 74F543_544_1 of 1994 Dec 05 (9397 750 05135).	
		Modifications:	
		 Remove part-type 74F544 and all its references. 	
		 Change Type number for SSOP24 package from "74F543DB" to "N74F543DB". 	
_2	19941205	Product specification (9397 750 05135). ECN 853-0874 14379 of 05 December 1994.	

Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions
I	Objective data sheet	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data sheet	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
111	Product data sheet	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Disclaimers

Life support — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes in the products—including circuits, standard cells, and/or software—described or contained herein in order to improve design and/or performance. When the product is in full production (status 'Production'), relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN). Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

Contact information

For additional information please visit http://www.semiconductors.philips.com. Fax:

Fax: +31 40 27 24825

All rights reserved. Printed in U.S.A.

© Koninklijke Philips Electronics N.V. 2004

For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com

Document order number:

Date of release: 07-04

9397 750 13803

Let's make things better.



